

Data sheet Product WLK DK 50



Thermal interface material / Fixing material / Mounting material>Thermal interface material>Thermally conductive adhesive

- solvent-free and thermal conductive two part adhesive
- epoxy based filled with aluminium oxide
- composition of hardener and resin (1:1) with statical mixing tube
- lockability of the container via Luer-Lock System
- good usage and working properties
- more package sizes and container types upon request
- store cool and dry

Features

thermal conductivity:	1 W/m·K
specific thermal resistance:	118°C cm/W
working life at room temperature:	approx. 30 min
hardening time:	60°C approx. 4 h/25°C approx. 16 h
volume resistance:	$8 \cdot 10^{11} \Omega/\text{cm}$
temperature range:	-50°C... +145°C
glue layer:	Epoxid
mixture proportion:	1:1
contents of delivery:	1x 50 ml cartridge / 3x mixer WLK M 50